

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image

























High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 5.08 mm, Number of poles: 21, 90°, Solder pin length (I): 3.2 mm, tinned, black, Box
Order No.	<u>1780370000</u>
Туре	SL-SMT 5.08HC/21/90G 3.2SN BK BX
GTIN (EAN)	4032248165698
Qty.	20 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Вох

Creation date March 25, 2021 7:10:37 AM CET



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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	11.6 mm	Height (inches)	0.457 inch
Height of lowest version	8.4 mm	Net weight	9.9 g
Width	109.88 mm	Width (inches)	4.326 inch

System specifications

Product family	OMNIMATE Signal - series	Type of connection	
	BL/SL 5.08		Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	
	connection		5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	90°
Number of poles	21	Number of solder pins per pole	1
Solder pin length (I)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tole	rance (D)+ 0,1 mm	L1 in mm	101.6 mm
L1 in inches	4 inch	Number of rows	1
Pin series quantity	1	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

Material data

	LODOS		
Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface		Layer structure of solder connection	13 µm Ni / 24 µm Sn
	tinned		matt
Layer structure of plug contact	13 μm Ni / 24 μm Sn	Storage temperature, min.	
	matt		-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2 4 kV		Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		



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Technical data

Rated data acc. to CSA

nstitute (CSA)	€P ·	Certificate No. (CSA)	
			200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

	see approval certificate.		
Rated data acc. to UL 1059			
Institute (UR)	<i>27</i> .	Certificate No. (UR)	
			E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
Packaging	Box	VPE length	30 mm
VPE width	50 mm	VPE height	120 mm

•					
ETIM 6.0	EC002637	ETIM 7.0	EC002637		
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02		
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01		
Important note					
IPC conformity	standards and norms an	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative propertie in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.			
Notes	Gold-plated contact s	Gold-plated contact surfaces on request			
	Rated current related to rated cross-section & min. No. of poles.				
	• Diameter of solder eyelet D = 1.4+0.1mm				
	• Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles				
	• P on drawing = pitch				
	•	to the component itself. Clearance and clance with the relevant application stand	reepage distances to other components are to ards.		
	Long term storage of	the product with average temperature of	50 °C and average humidity 70%, 36 months		



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Technical data

Approvals

Approvals



ROHS	Conform
UL File Number Search	E60693

Downloads

Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	STEP
Engineering Data	EPLAN, WSCAD, Zuken E3.S



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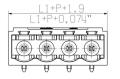
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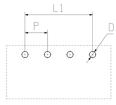
Drawings

Product image

Dimensional drawing





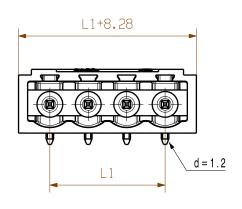


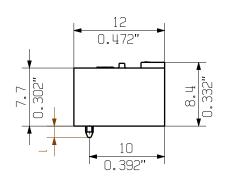
HOLE PATTERN

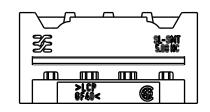
Product benefits

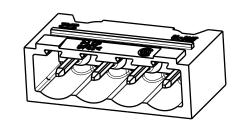


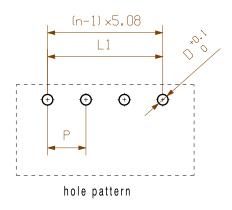
Safe power transmission Proven properties

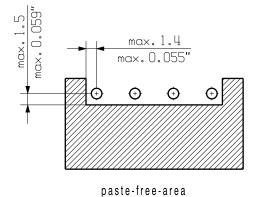












D= 1.4/0.055" or 1.5/0.059"(REFLOW SOLDERING) RECOMMENDATION FOR AUTOMATIC ASSEMBLY (1.4mm FOR n=2...8 / 1.5mm for n=9...24)

n = Polzahl / no of poles

P = Raster / pitch

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.

The neccessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.

The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application. Provided that the components are used to the intended purpose, all requirements with respect to the occuring of electrical, mechanical, thermic and corrosive stress will be satisfied.

shown: SL-SMT 5.08HC/04/90G

DIN ISO 2768-m

4.5	0.1/-0.3
3.2	0.1/-0.3
2.1	0.1/-0.3
1.5	-0.3
1	tolerance

22	106.68	4.200	
21	101.60	4.000	+/- 0.2
20	96.52	3.800	
19	91.44	3.600	
18	86.36	3.400	
17	81.28	3.200	
16	76.20	3.000	
15	71.12	2.800	
14	66.04	2.600	+/- 0.15
13	60.96	2.400	
12	55.88	2.200	
11	50.80	2.000	
10	45.72	1.800	
9	40.64	1.600	
8	35.56	1.400	
7	30.48	1.200	
6	25.40	1.000	
5	20.32	0.800	+/- 0.1
4	15.24	0.600	
3	10.16	0.400	
2	5.08	0.200	
no of poles	L1 [mm]	L1 [inch]	tolerance L1
Cat.no.:.			

33262

31

Issue no

sheets

116.84 4.600

111.76 4.400 106.68 4.200

24

23

COMPLIANT	106339/4 30.07.18 HE	RTEL_S	00	Weidmüller 🕏	
	Modification			vicialialici 2	
		Date		Name	
	Drawn	29.11.20	07	HELIS_MA	SL-SMT 5.
	Responsible			HERTEL_S	
Scale: 2:1	Checked	01.08.20	18	KOCH_JG	MALE H
Supersedes: .	Approved			LANG_T	Product file: SL-SMT 5.08

SL-SMT 5.08HC/../90...

STIFTLEISTE MALE HEADER

Product file: SL-SMT 5.08 7280

Drawing no.

Sheet 02



Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.



Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.